	Material Composition Declaration 	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-21.1	IPC Web Site for Information on IPC-1752 Standard **http://www.ipc.org/IPC-175x**	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company name* **onsemi**	Company unique ID	Unique ID Authority	**Response Date*** **2023-06-08**
Contact Name **Product-Env-Stewards**	Title - Contact Product Enviro Compliance	**Phone - Contact*** **NA**	**Email - Contact*** **Product-Env-Stewards@onsemi.com**
Authorized Representative* **Product-Env-Stewards**	Title - Representative Product Enviro Compliance	**Phone - Representative*** **NA**	**Email - Representative*** **Product-Env-Stewards@onsemi.com**

	Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
		AR0239SRSC00SUEA0-DRBR	2MP 1/3 CIS SO	2023-06-08		TA1	196.1	mg	Each

Manufacturing Proccess Information

	Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature		Max Time at Peak Temperature		Number of Reflow Cycles
	SnAgCu	**CU Alloy**	**4**	**260**	C	**30**	seconds	**3**

Comments

For more information regarding material composition please refer to page 3

RoHS Material Composition Declaration	**Declaration Type ***	**Detailed**

Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).

Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a “RoHS restricted substance”) in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components.Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form.Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph.If the Company and the Supplier enter into a written agreement with respect to the identified part,the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.

RoHS Declaration *	1 - Item(s) does not contain RoHS restricted substances per the definition above	**Supplier Acceptance ***	**Accepted**

Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version	EL-2011/534/EU	

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature	**Rastislav Drska**		

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	46.097	mg		Misc.	proprietary data		0.1752	mg
			Supplier	Silicon (Si)	7440-21-3		45.4655	mg
			Supplier	Aluminum (Al)	7429-90-5		0.4564	mg
Die Attach	2.811	mg		Bismaleimide Monomer	proprietary data		1.0822	mg
			Supplier	POLY(ETHYLENE GLYCOL) PHENYL ETHER ACRYLATE	56641-05-5		0.0141	mg
			Supplier	2,2-Bis(4-hydroxyphenyl)propane-epichlorohydrin copolymer acrylate	55818-57-0		0.2811	mg
			Supplier	Bis(4-tert-butylcyclohexyl) peroxydicarbonate	15520-11-3		0.0141	mg
			Supplier	2,2-dimethyl-1,3-propanediyl dimethacrylate	1985-51-9		0.2811	mg
			Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.2811	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0141	mg
			Supplier	Other Additive Agents	Proprietary Data		0.5622	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.2811	mg
Epoxy	1.438	mg	Supplier	Imidazole Addition	68490-66-4		0.4314	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.1438	mg
			Supplier	Zirconium Dioxide (ZrO2)	1314-23-4		0.1438	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.1438	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.5752	mg
Imaging Lens	28.822	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.5169	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.5169	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.5169	mg
			B	Antimony Trioxide (Sb2O3)	1309-64-4		0.1519	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.5169	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.5169	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		21.0856	mg
Mold Compound	42.869	mg		Epoxy resin	proprietary data		10.6315	mg
			Supplier	Other Additive Agents	Proprietary Data		1.3718	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.2869	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.2927	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.2861	mg

Solder Ball	35.356	mg	Supplier	Silver (Ag)	7440-22-4		1.0607	mg
			Supplier	Tin (Sn)	7440-31-5		34.1185	mg
			Supplier	Copper (Cu)	7440-50-8		0.1768	mg
Solder Mask	4.15	mg		Epoxy resin	proprietary data		0.498	mg
			Supplier	Acrylate	Proprietary Data		1.5853	mg
			Supplier	Talc	14807-96-6		0.1121	mg
			Supplier	Miscellaneous	Trade Secret		0.1535	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		1.8011	mg
Substrate Copper Foil	3.194	mg	Supplier	Copper (Cu)	7440-50-8		3.194	mg
Substrate - Core Material	15.866	mg		Epoxy resin	proprietary data		3.4382	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		12.4278	mg
Substrate Plating-Au	0.275	mg	Supplier	Gold (Au)	7440-57-5		0.275	mg
Substrate Plating-Cu	14.28	mg	Supplier	Copper (Cu)	7440-50-8		14.28	mg
Substrate Plating-Ni	0.66	mg	B	Nickel (Ni)	7440-02-0		0.66	mg
Wire Bond - Au	0.282	mg	Supplier	Gold (Au)	7440-57-5		0.282	mg